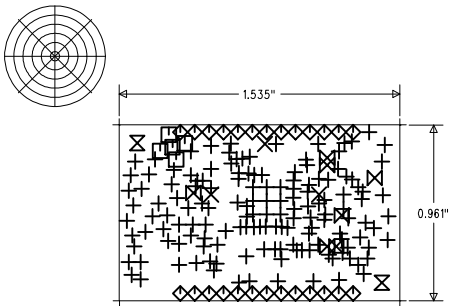


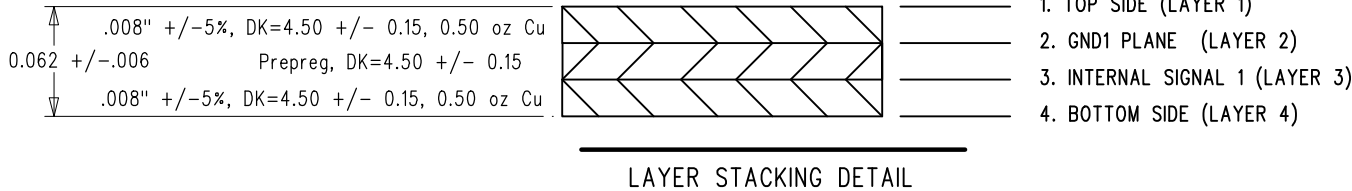
R E V I S I O N S				
ECO	REV	DESCRIPTION	DATE	APPROVED
1071	1	Initial Release	12/27/11	

FABRICATION NOTES:

1. FABRICATION: FABRICATION AND ACCEPTANCE TO MEET THE REQUIREMENTS OF IPC-A-600 AND IPC/ANSI-MLL950-C CLASS 2, AQL .25 GENERAL INSPECTION LEVEL
II. ACCEPTANCE STAMP NO LARGER THAN 0.25 INCH IS TO BE LOCATED ON THE SOLDER SIDE USING CONTRASTING (WHITE PREFERRED) NONCONDUCTIVE PERMANENT INK.
USE ROHS-COMPLIANT MATERIAL.
2. ALL BOARD DIMENSIONS IN INCHES. TOLERANCE = ± 0.003 " UNLESS NOTED OTHERWISE.
3. MATERIAL: NATURAL EPOXY/GLASS LAMINATES PCL-370HR OR EQUIVALENT ROHS-COMPLIANT MATERIAL.
GLASS TRANSITION TEMPERATURE MUST MEET OR EXCEED THAT REQUIRED FOR LEAD-FREE PROCESSING. MATERIAL SHALL BE UL94V-0 FLAMMABILITY RATED.
4. OUTER LAYER COPPER THICKNESS 0.0007" (1/2 OZ) FINISHED. INNER LAYER COPPER THICKNESS 0.0007" (1/2 OZ).
5. FINISH: GOLD IMMERSION, 2-5 MICRO INCHES (ROHS COMPLIANT).
6. SOLDER MASK: ROHS COMPLIANT, LPI SOLDER MASK PER IPC-SM-840C, OVER BARE COPPER (SMOBC) BOTH SIDES. REGISTRATION TO BE WITHIN ± 0.002 OF THE ASSOCIATED CIRCUIT LAYER, WITH NO MASK APPEARING ON PADS. PRESENCE OF SOLDER MASK RESIDUE SCRATCHES, AND/OR CONTAMINATION WHICH IMPAIR CONTACT PERFORMANCE ARE CONSIDERED MAJOR DEFECTS, AND CAUSE FOR LOT REJECTION. COLOR: BLUE.
7. HOLE CENTERS AND PAD CENTERS TO BE CONCENTRIC WITHIN 0.003"
8. THE END PRODUCT THAT THIS PCB IS USED ON HAS BEEN SUBMITTED FOR INTRINSIC SAFETY APPROVAL
ANY CHANGES IN DESIGN, COMPONENTS, OR BOARD LAYOUT MAY AFFECT APPROVAL AND REQUIRE RE-SUBMITTAL.
9. MARKINGS: DATE CODE AND UL RECOGNIZED VENDOR MARK TO BE SILKSCREEN ON SECONDARY SIDE
SILKSCREEN LEGEND "PCB DOM:WW-YY" SHALL BE
CHANGED TO ACTUAL YEAR (YY) AND WEEK (WW) FAB WAS MANUFACTURED.
10. SILKSCREEN: SILKSCREEN LEGEND OVER SOLDER MASK, BOTH SIDES. MATERIAL TO BE WHITE ELECTRICALLY
NONCONDUCTIVE INK, NO INK TO APPEAR ON COMPONENT
PADS, FIDUCIALS, ELECTRICALLY EXPOSED VIAS OR MOUNTING HOLES. MINIMUM TEXT HEIGHT TO BE 0.040" WITH
0.004" STROKE WIDTH, OVERLAP ONTO TENTED HOLES ALLOWED. USE ROHS-COMPLIANT MATERIAL.
11. PANELIZATION: PANELIZE 10 AS SPECIFIED IN PANEL DRAWING.
ALLOW DUST ENGINEERING TO REVIEW & APPROVE FINAL ARRAY CAM BEFORE BUILDING.
PANEL DRAWING FOR MECHANICAL EXTENTS ONLY. DO NOT USE PANEL DRAWING FOR DRILL INFORMATION.
12. ELECTRICAL TEST: TEST ALL BOARDS, INCLUDING ALL PLATED HOLES, PADS AND ANY FINGERS.
CONTINUITY METER LIMITS: MIN. 40V, MAX 300 mA.
MAX CONTINUOUS NET RESISTANCE = 5 OHM
MIN ISOLATED NET RESISTANCE = 15 MOHM
MARK TEST PASS USING CONTRASTING, INDELIBLE INK, ON BOTTOM SIDE (DRILLDWG.PHO)
13. HOLES, VIA'S: HOLE SIZES GIVEN IN TABLE ARE "FINISHED" HOLE SIZE. PLATED THROUGH HOLES SHALL
HAVE MINIMUM COPPER THICKNESS OF 0.001"
14. EACH LOT MUST INCLUDE ONE SOLDER SAMPLE AND ONE CORE SAMPLE.
15. REPORT: PROVIDE WRITTEN 1ST ARTICLE REPORT AND PHYSICAL SAMPLE WITH FIRST SHIPMENT.
PROVIDE POLISHED CROSS-SECTION SAMPLE (INCLUDE ALL CU LAYERS & A PLATED HOLE)
INSPECTION DATA OF CROSS-SECTION.
MEASUREMENT OF METAL THICKNESS.
CERTIFICATE OF CONFORMANCE TO BE PROVIDED FOR ALL SHIPMENTS, INCLUDING
- SUPPLIER NAME, ADDRESS, PN, PLACE & DATE OF ISSUE, AND AUTHORIZED SIGNATURE.
- ANY REFERENCED STANDARDS
- SUPPLEMENTARY INFORMATION INCLUDING TRACEABILITY DATA.
16. INTERPRET DIMENSIONS PER ANSI-Y14.5.



SIZE	QTY	SYM	PLATED	TOL
0.01	148	⊕	YES	+/-0.003
0.02	3	⊗	NO	+/-0.003
0.031	5	□	YES	+/-0.003
0.035	26	◇	YES	+/-0.003
0.094	2	⊗	YES	+/-0.003
0.018	7	⊗	YES	+/-0.003



THE FAB SHALL BE ROHS-COMPLIANT.

		UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES:	APPROVALS	DATE	TITLE: FABRICATION DRAWING, PCB, SIP MOTE CARRIER, BEAR, ROHS			
		TOLERANCES ARE: FRACTIONS: DECIMALS: .XX \pm .01 ANGLES: 0° 30' .XXX \pm .003	DRAWN BY:	12-27				
			ROSS P. DANIELS	-11				
			CHECKED					
SEE ARENA			ENGRG					
NEXT ASSY	USED ON	MATERIAL - SEE NOTES.	ISSUED		B	FSCM NO.	DWG NO.	REV.
APPLICATION		FINISH - SEE NOTES.	CONTRACT NO.				615-0183	1
		DO NOT SCALE DRAWING				SCALE: NONE		SHEET 1 OF 1